



Click [here](#) for the 3D model.

### Dimensions

|   |                 |
|---|-----------------|
| L | 1.6mm +/-0.2mm  |
| W | 3.2mm +/-0.2mm  |
| T | 0.8mm +/-0.10mm |
| P | 0.8mm +/-0.10mm |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

### General Information

|                          |  |
|--------------------------|--|
| Series                   | Array Auto COG Flex                                  |
| Style                    | SMD Array  |
| Description              | SMD, MLCC, Array, Flex Termination, Automotive Grade |
| Features                 | Automotive Grade                                     |
| RoHS                     | Yes  |
| Termination              | Flexible Termination                                 |
| Qualifications           | AEC-Q200   |
| AEC-Q200                 | Yes  |
| Typical Component Weight | 18 mg  |
| Notes                    | Last Time Buy Date (LTB): May 30th, 2024.            |
| Chip Size                | 0612   |
| Shelf Life               | 78 Weeks   |
| MSL                      | 1  |

### Specifications

|  |                        |
|--|------------------------|
| Capacitance  | 15 pF                  |
| Measurement Condition  | 1MHz 1.0Vrms           |
| Capacitance Tolerance  | 20%                    |
| Voltage DC   | 10 VDC                 |
| Dielectric Withstanding Voltage                                    | 25 VDC                 |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1MHz 1.0Vrms      |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |